

WHAT IS CLAIMED IS:

1. A method of making photosensitive chips for use in an imaging apparatus, comprising the steps of:

providing an integrated circuit wafer, the wafer comprising a first chip area defined in a main surface of the wafer, the first chip area including structure related to a first photosite, and a groove defined in the wafer, the groove defining at least one edge of the first chip area; providing a light-transmissive planar layer over the main surface, the planar layer forming a planar surface substantially parallel with the main surface, the planar layer extending over the groove; and

dicing the wafer along the groove.

2. The method of **claim 1**, the planar layer comprising acrylic.

3. The method of **claim 1**, further comprising the step of providing a filtering layer disposed over the planar layer.

4. The method of **claim 3**, the filtering layer extending over the first photosite and over the groove.

5. The method of **claim 3**, the filtering layer comprising acrylic.

6. The method of **claim 1**, further comprising the step of providing in the chip area a ridge defined on the main surface between the photosite and the groove.

7. The method of **claim 1**, further comprising the step of providing in the chip area a ridge defined on the main surface between the photosite and the groove.